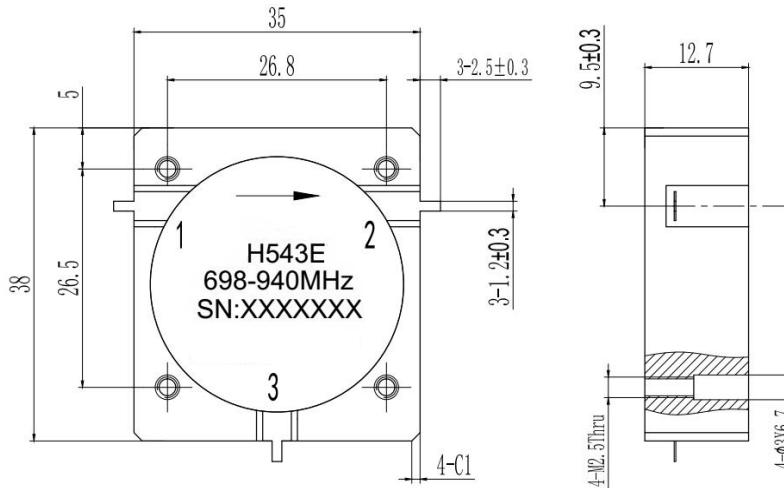


1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

Part No.	Frequency (GHz)		Center Frequnc (GHz)	Bandwidth (GHz)	Isolation (dB) MIN	INS LOSS (dB) MAX	VSWR (dB) MAX	Power (W)	IMD (@2X43dBm (-dBc) MAX
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H543E [330-350]MHz	0.330	0.350	0.340	0.020	20	0.45	1.22	100	
H543E [400-430]MHz	0.400	0.430	0.4250	0.030	22	0.25	1.17	200	
H543E [470-570]MHz	0.470	0.570	0.5200	0.100	20	0.4	1.2	200	
H543E [500-650]MHz	0.500	0.650	0.5750	0.150	18	0.45	1.28	100	
H543E [698-940]MHz	0.698	0.940	0.8190	0.242	18	0.4	1.28	100	